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#2 *Pat. Authorization*
7-25-01
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Atty.Docket No.: 12597-P66182USO
CUSTOMER NUMBER: 00136

Assistant Commissioner of Patents
Washington, D.C. 20231
Sir:

Transmitted herewith for filing is the patent application in the name of

MUN, Young-Hee of Gumi-shi, Republic of Korea,

for **METHOD OF TREATING SEMICONDUCTOR WAFER THERMALLY AND SEMICONDUCTOR WAFER FABRICATED BY THE SAME.** The application comprises a 20-page specification including 19 claims (5 independent) and Abstract, 3 sheets of drawings (Figs. 1 to 3), and a Declaration and Power of Attorney.

Also accompanying this application for filing are:

- (1) Assignment document, cover sheet and \$40.00 fee for recordation of Assignment;
- (2) A certified copy of Korean Application No. 2000-58101, filed **October 4, 2000**, the priority of which is claimed under 35 U.S.C. §119; and
- (3) Information Disclosure Statement, PTO-1449 form and Copies of References.

The filing fee has been calculated as shown:

Large Entity			\$ 710.00
Total Claims	<u>19</u> in excess of 20 = 0(x \$18.00)	=	0.00
Total Ind. Claims	<u>05</u> in excess of 03 = 2(x \$78.00)	=	156.00
		+	
TOTAL FILING FEES:			\$ 866.00

A check in the amount of \$906.00, is enclosed to cover the Filing Fee. The Commissioner is hereby authorized to charge payment of any fees set forth in Sections 1.16 or 1.17 during the pendency of this application, or credit any overpayment, to deposit Account No. 06-1358. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

By: 

Yoon S. Ham

Reg. No. 45,307

Enclosures
YSH:ecl

